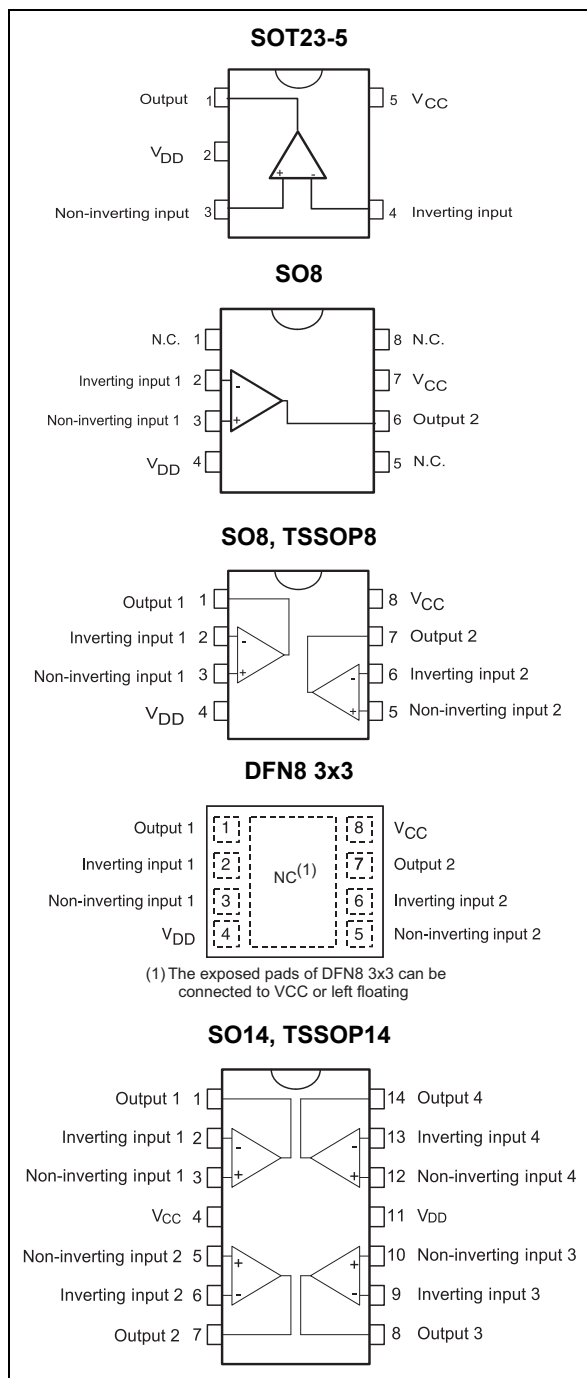


Output rail-to-rail very low noise operational amplifier

Datasheet - production data



Features

- Rail-to-rail output voltage swing ± 2.4 V at $V_{CC} = \pm 2.5$ V
- Very low noise level: 4 nV/ $\sqrt{\text{Hz}}$
- Ultra low distortion: 0.003 %
- High dynamic features: 12 MHz, 4 V/ μs
- Operating range: 2.7 to 10 V
- ESD protection (2 kV)
- Latch-up immunity (class A)

Applications

- Portable devices (CD players, PDAs)
- Portable communication (cell phones, pagers)
- Instrumentation and sensing technology
- Professional audio circuits

Description

The TS97x family of operational amplifiers operate with voltages as low as ± 1.35 V and feature output rail-to-rail signal swing. The TS97x devices are particularly well suited for portable and battery supplied equipment. Very low noise and low distortion characteristics make them ideal for audio pre-amplification.

The TS97x devices are available in a variety of packages to suit all types of applications. For applications where space saving is critical, the SOT23-5 package (2.8 x 2.9 mm) or the DFN8 package (3 x 3 mm) simplify the board design because they can be placed anywhere on it.

Contents

1	Absolute maximum ratings and operating conditions	3
2	Electrical characteristics	5
3	Package information	8
3.1	SOT23-5 package information	9
3.2	SO8 package information	10
3.3	TSSOP8 package information	11
3.4	DFN8 3x3 exposed pad package information	12
3.5	SO14 package information	13
3.6	TSSOP14 package information	14
4	Ordering information	15
5	Revision history	16

1 Absolute maximum ratings and operating conditions

Table 1. Absolute maximum ratings (AMR)

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage ⁽¹⁾	12	V
V_{id}	Differential input voltage ⁽²⁾	± 1	
V_{in}	Input voltage ⁽³⁾	$V_{DD} - 0.3$ to $V_{CC} + 0.3$	
T_{stg}	Storage temperature range	-65 to +150	°C
T_j	Maximum junction temperature	150	
R_{thja}	Thermal resistance junction-to-ambient ⁽⁴⁾		°C/W
	SOT23-5	250	
	SO8	125	
	TSSOP8	120	
	DFN8 3x3	40	
	SO14	105	
	TSSOP14	100	
R_{thjc}	Thermal resistance junction-to-case ⁽⁴⁾		
	SOT23-5	81	
	SO8	40	
	TSSOP8	37	
	DFN8 3x3	5.2	
	SO14	31	
	TSSOP14	32	
ESD	HBM: human body model ⁽⁵⁾	2	kV
	MM: machine model ⁽⁶⁾	200	V
	CDM: charged device model ⁽⁷⁾	1.5	kV
	Lead temperature (soldering, 10 sec.)	260	°C

1. All voltage values, except differential voltage are with respect to network ground terminal.
2. The differential voltage is the non-inverting input terminal with respect to the inverting input terminal.
3. The magnitude of input and output voltages must never exceed $V_{CC} + 0.3$ V.
4. Short-circuits can cause excessive heating and destructive dissipation. Values are typical.
5. Human body model: a 100 pF capacitor is charged to the specified voltage, then discharged through a 1.5k Ω resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are floating.
6. Machine model: a 200 pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 Ω). This is done for all couples of connected pin combinations while the other pins are floating.
7. Charged device model: all pins and package are charged together to the specified voltage and then discharged directly to ground through only one pin. This is done for all pins.
No value specified for CDM on SOT23-5 package.

Table 2. Operating conditions

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	2.7 to 10	V
V_{icm}	Common mode input voltage range	$V_{DD} + 1.15$ to $V_{CC} - 1.15$	
T_{oper}	Operating free air temperature range	-40 to +125	°C

2 Electrical characteristics

**Table 3. Electrical characteristics at $V_{CC} = +2.5\text{ V}$, $V_{DD} = -2.5\text{ V}$, $T_{amb} = 25\text{ °C}$
(unless otherwise specified)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{io}	Input offset voltage	$T_{min} \leq T_{amb} \leq T_{max}$		1	5 7	mV
$\Delta V_{io}/\Delta T$	Input offset voltage drift	$V_{icm} = 0\text{ V}$, $V_o = 0\text{ V}$		5		$\mu\text{V}/^\circ\text{C}$
I_{io}	Input offset current	$V_{icm} = 0\text{ V}$, $V_o = 0\text{ V}$		10	150	nA
I_{ib}	Input bias current	$V_{icm} = 0\text{ V}$, $V_o = 0\text{ V}$ $T_{min} \leq T_{amb} \leq T_{max}$		200 200	750 1000	
V_{icm}	Common mode input voltage range		-1.35		1.35	V
CMR	Common mode rejection ratio	$V_{icm} = \pm 1.35\text{ V}$	60	85		dB
SVR	Supply voltage rejection ratio	$V_{CC} = \pm 2\text{ V}$ to $\pm 3\text{ V}$	60	70		
A_{vd}	Large signal voltage gain		70	80		
V_{OH}	High level output voltage	$R_L = 2\text{ k}\Omega$	2	2.4		V
V_{OL}	Low level output voltage			-2.4	-2	
I_{source}	Output source current			1.5		mA
I_{sink}	Output sink current			100		
I_{CC}	Supply current per amplifier	Unity gain - no load		2	2.8	
GBP	Gain bandwidth product	$f = 100\text{ kHz}$, $R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$	8.5	12		MHz
SR	Slew rate	$A_V = 1$, $V_{in} = \pm 1\text{ V}$	2.8	4		V/ μs
ϕ_m	Phase margin at unit gain	$R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$		60		Degrees
Gm	Gain margin			10		dB
e_n	Equivalent input noise voltage	$f = 100\text{ kHz}$		4		nV/ $\sqrt{\text{Hz}}$
i_n	Equivalent input noise current	$f = 1\text{ kHz}$		250		fA/ $\sqrt{\text{Hz}}$
THD	Total harmonic distortion	$f = 1\text{ kHz}$, $A_V = -1$, $R_L = 10\text{ k}\Omega$		0.003		%

Figure 1. Input offset voltage distribution

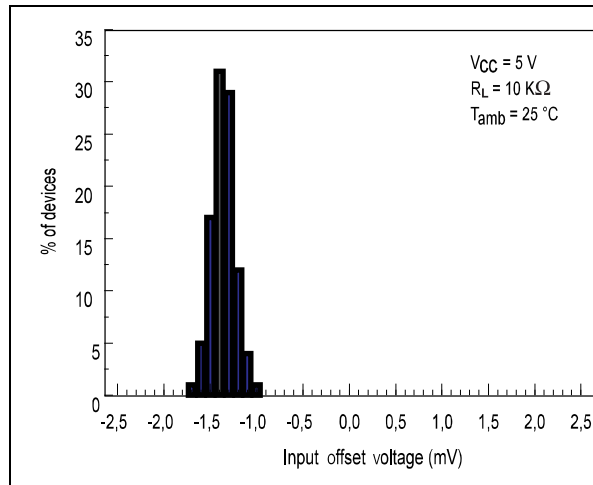
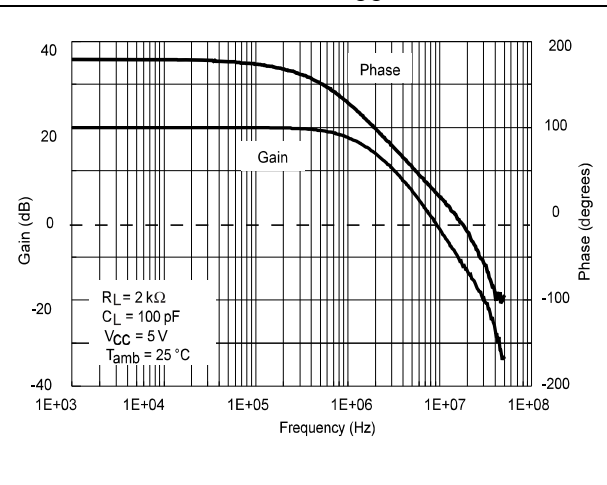
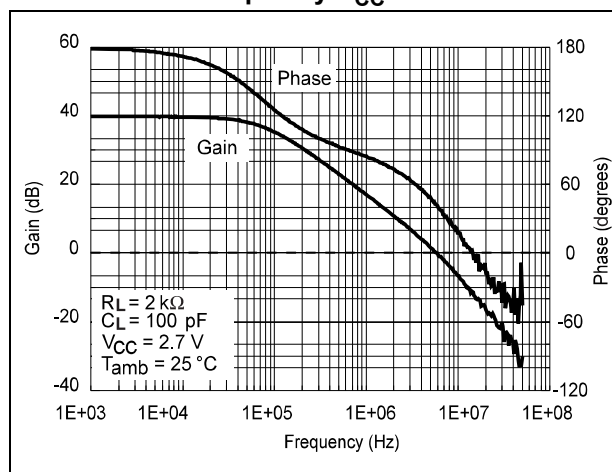
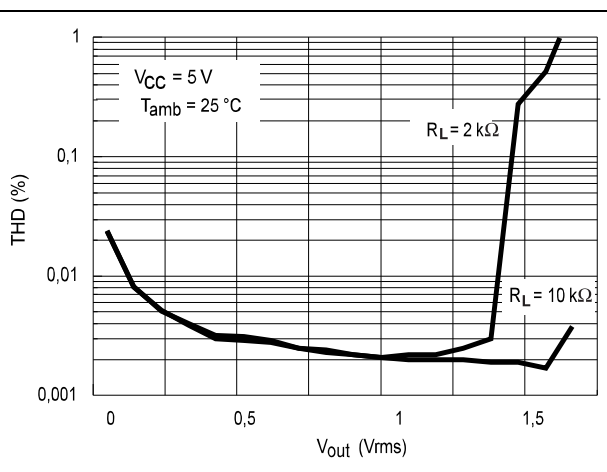
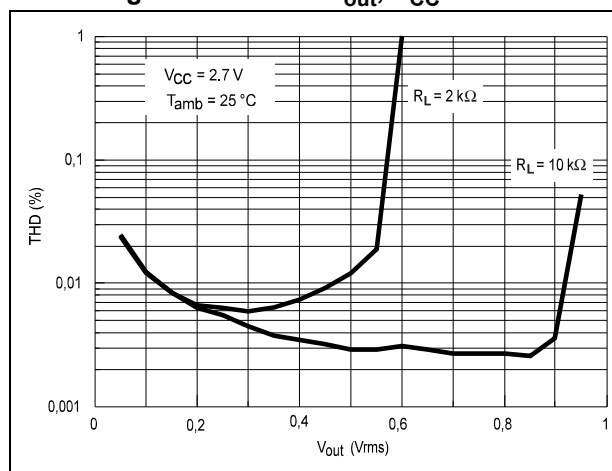
Figure 2. Voltage gain and phase vs. frequency $V_{CC} = 5\text{ V}$ Figure 3. Voltage gain and phase vs. frequency $V_{CC} = 2.7\text{ V}$ Figure 4. THS vs. V_{out} , $V_{CC} = 5\text{ V}$ Figure 5. THD vs. V_{out} , $V_{CC} = 2.7\text{ V}$ 

Figure 6. THD vs. frequency

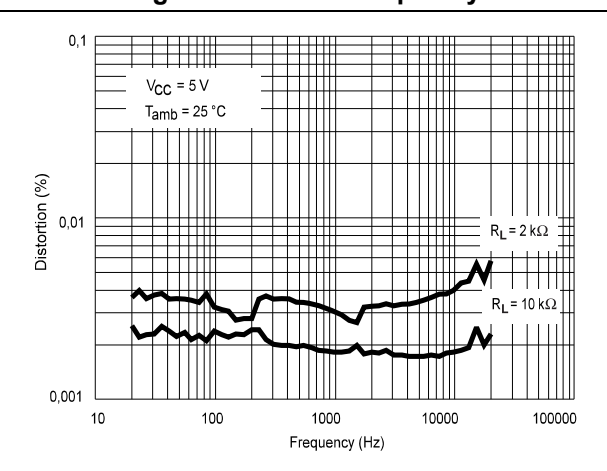
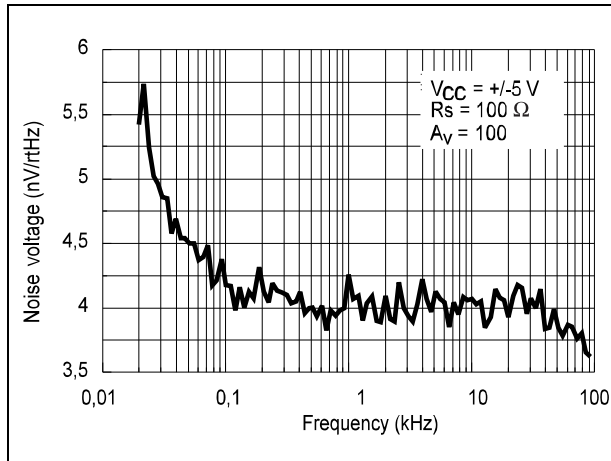
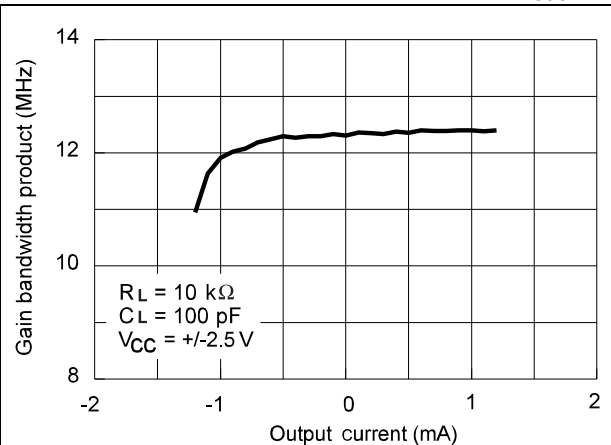
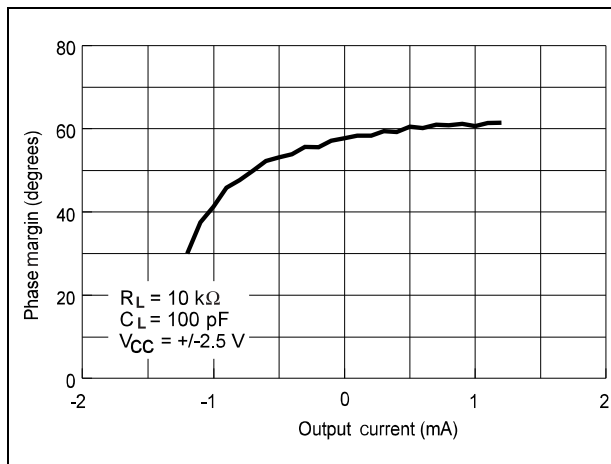
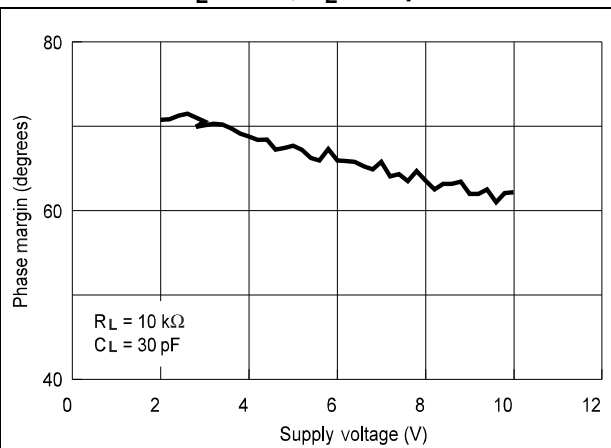
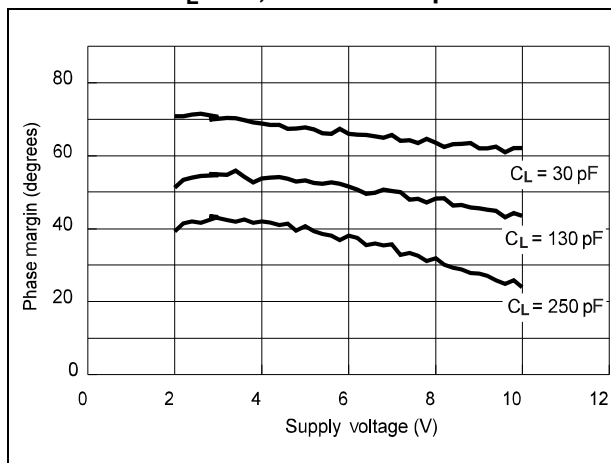
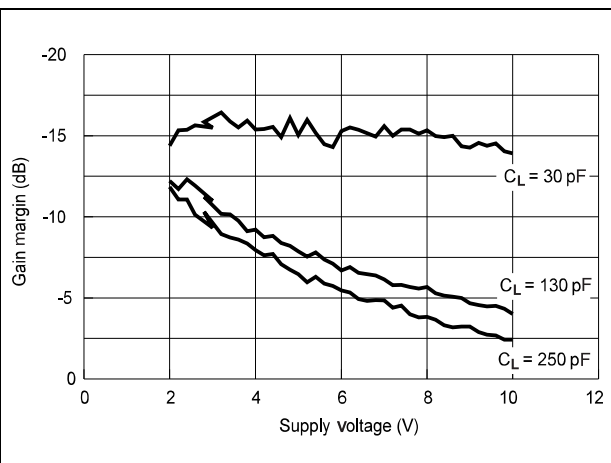


Figure 7. Noise voltage vs. frequency

Figure 8. Gain bandwidth product vs. I_{out} Figure 9. Phase margin vs. I_{out} Figure 10. Phase margin vs. V_{CC}
 $R_L = 10\text{ k}\Omega$, $C_L = 30\text{ pF}$ Figure 11. Phase margin vs. V_{CC}
 $C_L = 30, 130\text{ and }250\text{ pF}$ Figure 12. Gain margin vs. V_{CC} 

3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 SOT23-5 package information

Figure 13. SOT23-5 package outline

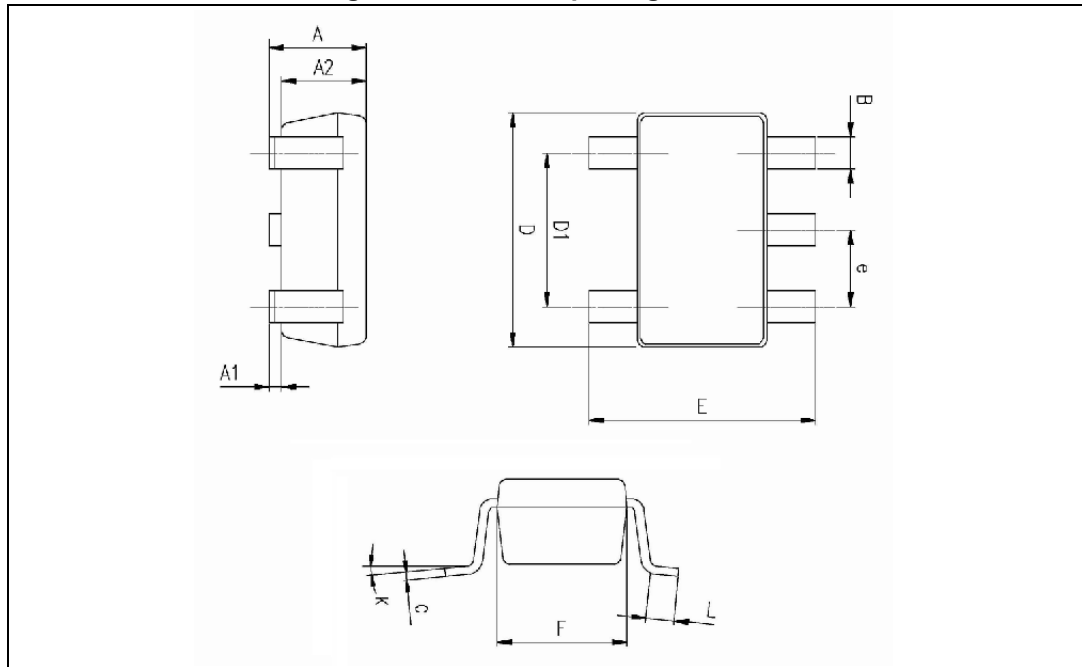


Table 4. SOT23-5 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90	1.20	1.45	0.035	0.047	0.057
A1			0.15			0.006
A2	0.90	1.05	1.30	0.035	0.041	0.051
B	0.35	0.40	0.50	0.013	0.015	0.019
C	0.09	0.15	0.20	0.003	0.006	0.008
D	2.80	2.90	3.00	0.110	0.114	0.118
D1		1.90			0.075	
e		0.95			0.037	
E	2.60	2.80	3.00	0.102	0.110	0.118
F	1.50	1.60	1.75	0.059	0.063	0.069
L	0.10	0.35	0.60	0.004	0.013	0.023
K	0 °		10 °	0 °		10 °

3.2 SO8 package information

Figure 14. SO8 package outline

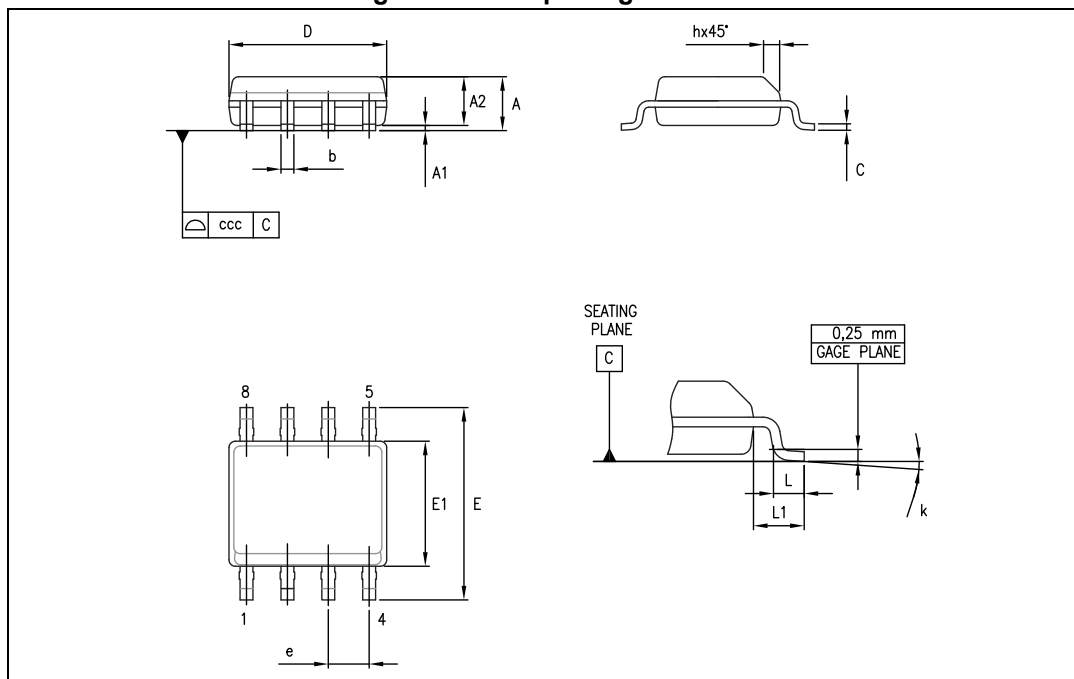


Table 5. SO8 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.069
A1	0.10		0.25	0.004		0.010
A2	1.25			0.049		
b	0.28		0.48	0.011		0.019
c	0.17		0.23	0.007		0.010
D	4.80	4.90	5.00	0.189	0.193	0.197
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e		1.27			0.050	
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
L1		1.04			0.040	
k	0 °		8 °	1 °		8 °
ccc			0.10			0.004

3.3 TSSOP8 package information

Figure 15. TSSOP8 package outline

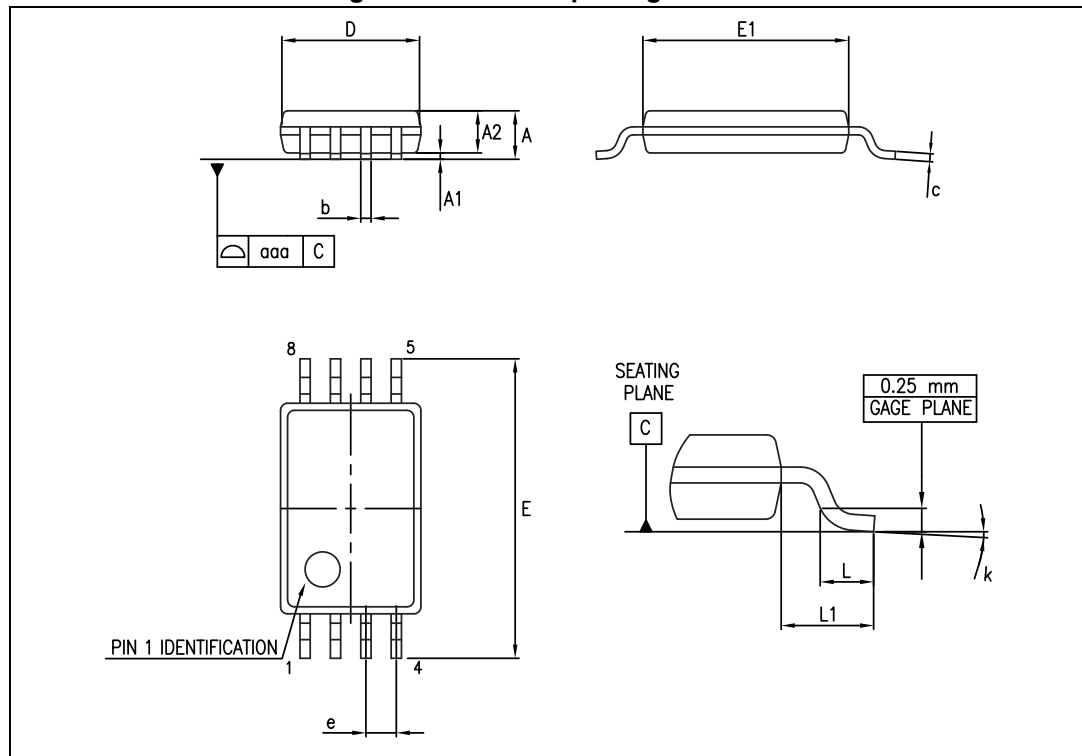


Table 6. TSSOP8 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.20			0.047
A1	0.05		0.15	0.002		0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.008
D	2.90	3.00	3.10	0.114	0.118	0.122
E	6.20	6.40	6.60	0.244	0.252	0.260
E1	4.30	4.40	4.50	0.169	0.173	0.177
e		0.65			0.0256	
k	0 °		8 °	0 °		8 °
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1.00			0.039	
aaa			0.10			0.004

3.4 DFN8 3x3 exposed pad package information

Figure 16. DFN8 3x3 exposed pad package outline (pitch 0.5 mm)

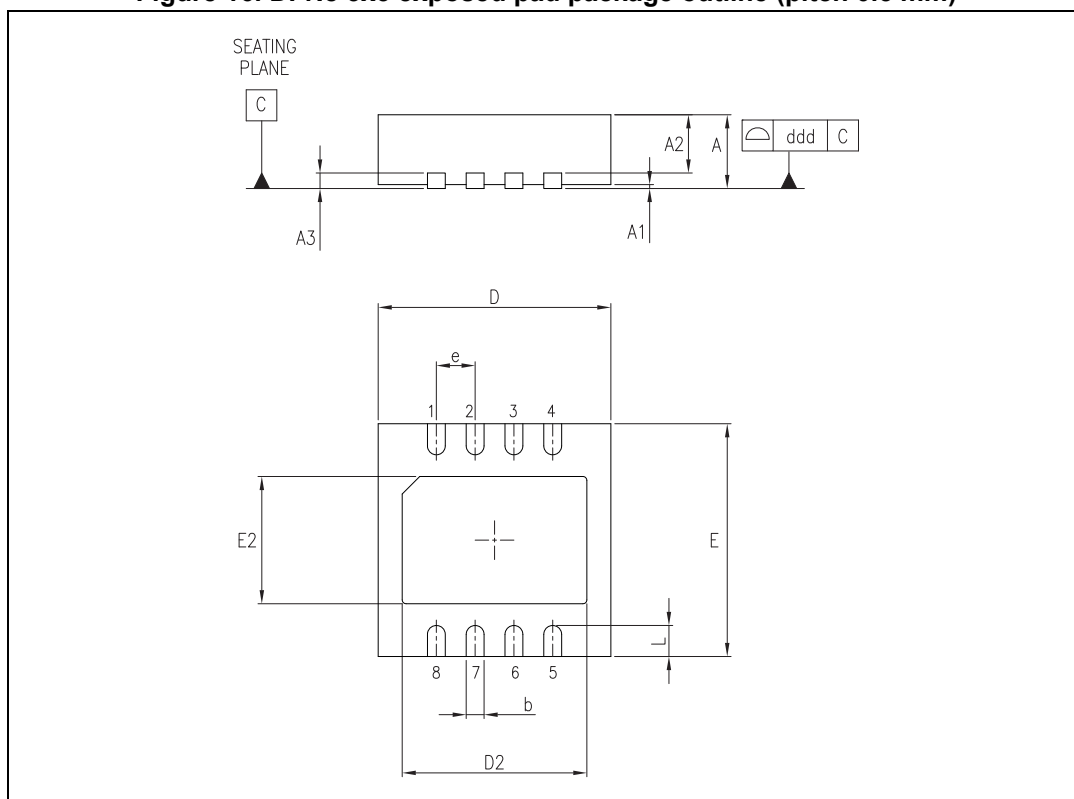


Table 7. DFN8 3x3 mm exposed pad package mechanical data (pitch 0.5 mm)

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.80	0.90	1.00	0.031	0.035	0.039
A1		0.02	0.05		0.0008	0.0019
A2	0.55	0.65	0.80	0.021	0.025	0.031
A3		0.20			0.008	
b	0.18	0.25	0.30	0.007	0.010	0.012
D	2.85	3.00	3.15	0.112	0.118	0.124
D2	2.20		2.70	0.087		0.106
E	2.85	3.00	3.15	0.112	0.118	0.124
E2	1.40		1.75	0.055		0.069
e		0.50			0.020	
L	0.30	0.40	0.50	0.012	0.016	0.020
ddd			0.08			0.003

3.5 SO14 package information

Figure 17. SO14 package outline

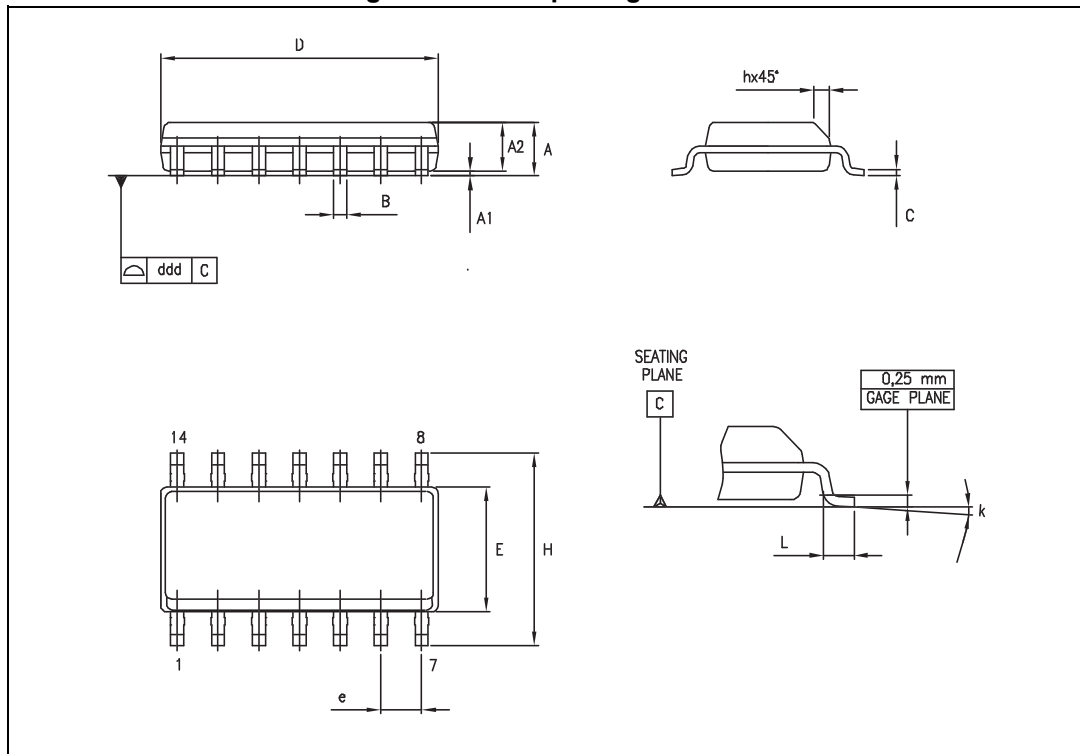


Table 8. SO14 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.35		1.75	0.05		0.068
A1	0.10		0.25	0.004		0.009
A2	1.10		1.65	0.04		0.06
B	0.33		0.51	0.01		0.02
C	0.19		0.25	0.007		0.009
D	8.55		8.75	0.33		0.34
E	3.80		4.0	0.15		0.15
e		1.27			0.05	
H	5.80		6.20	0.22		0.24
h	0.25		0.50	0.009		0.02
L	0.40		1.27	0.015		0.05
k	8 ° (max.)					
ddd			0.10			0.004

3.6 TSSOP14 package information

Figure 18. TSSOP14 package outline

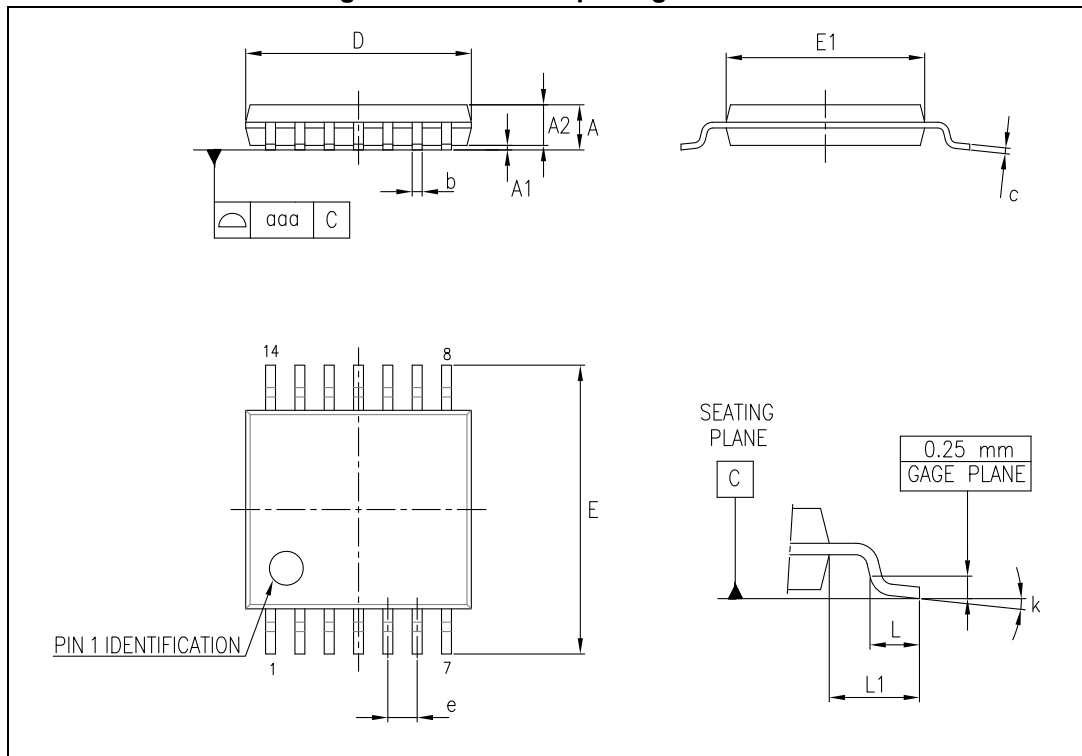


Table 9. TSSOP14 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.20			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.90	5.00	5.10	0.193	0.197	0.201
E	6.20	6.40	6.60	0.244	0.252	0.260
E1	4.30	4.40	4.50	0.169	0.173	0.176
e		0.65			0.0256	
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1.00			0.039	
k	0 °		8 °	0 °		8 °
aaa			0.10			0.004

4 Ordering information

Table 10. Order codes

Order code	Temperature range	Package	Packaging	Marking
TS971IDT	-40 °C, +125 °C	SO8	Tube or tape and reel	971I
TS971ILT		SOT23-5	Tape and reel	K120
TS971IYLT ⁽¹⁾		SOT23-5 (automotive grade level)		K121
TS972IDT		SO8	Tube or tape and reel	972I
TS972IPT		TSSOP8 (thin shrink outline package)	Tape and reel	
TS972IQT		DFN8 3x3 (dual micro lead frame package)		
TS972IYDT ⁽¹⁾		SO8 (automotive grade level)	Tube or tape and reel	972IY
TS972IYPT ⁽¹⁾		TSSOP8 (automotive grade level)	Tape and reel	972IY
TS974IDT		SO14	Tube or tape and reel	974I
TS974IPT		TSSOP14 (thin shrink outline package)	Tape and reel	
TS974IYDT ⁽¹⁾		SO14 (automotive grade level)		974IY
TS974IYPT ⁽¹⁾		TSSOP14 (automotive grade level)		974IY

1. Qualified and characterized according to AEC Q100 and Q003 or equivalent, advanced screening according to AEC Q001 and Q 002 or equivalent.

5 Revision history

Table 11. Document revision history

Date	Revision	Changes
15-Nov- 2002	1	First release.
9-May- 2005	2	Modifications on AMR table (explanation of V_{id} and V_i limits)
31-Aug-2005	3	PPAP references inserted in the datasheet, see Table 1 on page 2.
9-Dec-2005	4	Thermal resistance junction to case data added in Table 1. on page 3 Missing PPAP references inserted in the datasheet, see Table 10: Order codes .
3-Oct-2007	5	Added R_{thja} and R_{thjc} values for DIP8 and DIP14 packages in Table 1 . ESD footnotes updated in Table 1: Absolute maximum ratings (AMR) . Description section updated on cover page. Markings for automotive grade parts corrected in Table 10: Order codes .
20-Dec-2007	6	Reformatted package information in Section 3: Package information . Footnotes for automotive grade parts corrected in Table 10: Order codes .
06-May-2010	7	Updated package information (drawings and data) in Chapter 3 . Removed DIP package order codes from Chapter 4: Ordering information .
19-Sep-2012	8	Updated "Pin connection" figure on page 1 (removed part numbers). Removed TS971ID, TS971IYD, TS972ID, TS972IYD, TS974ID and TS974IYD order code from Table 10 . Qualified status of TS971IYLT and TS974IYPT order code in Table 10 . Minor corrections throughout document.
19-Jul-2013	9	Added footnote regarding NC to the DFN8 3x3 pinout Table 10: Order codes : removed order code TS971IYDT; added automotive qualification to order code TS972IYPT.
07-Mar-2014	10	Table 3: Electrical characteristics at $V_{CC} = +2.5\text{ V}$, $V_{DD} = -2.5\text{ V}$, $T_{amb} = 25\text{ }^{\circ}\text{C}$ (unless otherwise specified) : added parameter "equivalent input noise current"

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2014 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

